

LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIER

Check for Samples: TL072-EP, TL074-EP

FEATURES

- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion: 0.003% Typ
- Low Noise

 $V_n = 18 \text{ nV}/\sqrt{\text{Hz}}$ Typ at f = 1 kHz

- High Input Impedance: JFET Input Stage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate: 13 V/μs Typ
- Common-Mode Input Voltage Range Includes V_{CC+}

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly and Test Site
- One Fabrication Site
- Available in Extended (–40°C to 125°C) or Military (–55°C to 125°C) Temperature Range
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability

DESCRIPTION/ORDERING INFORMATION

The JFET-input operational amplifiers in the TL07x is similar to the TL08x series, with low input bias and offset currents and fast slew rate. The low harmonic distortion and low noise make the TL07x ideally suited for high-fidelity and audio preamplifier applications. Each amplifier features JFET inputs (for high input impedance) coupled with bipolar output stages integrated on a single monolithic chip.

The TL07x is characterized for operation over the extended temperature range of -40° C to 125° C or military temperature range of -55° C to 125° C.

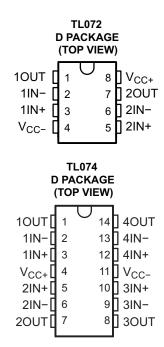
ORDERING INFORMATION⁽¹⁾

T _A	V _{IO} maX AT 25°C PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING	VID NUMBER	
40°C to 125°C	6 mV	SOIC - D	Reel of 2500	TL072QDREP	TL072Q	V62/12604-01XE
–40°C to 125°C	OIIIV	30IC - D	Reel of 2500	TL074QDREP	TL074Q	V62/11621-01XE
55°C to 125°C	5°C to 125°C 6 mV	SOIC - D	Reel of 2500	TL074MDREP	TL074M	V62/11621-02XE
-55°C to 125°C		201C – D	Tube of 75	TL074MDEP	TL074M	V62/11621-02XE-T

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI
website at www.ti.com.

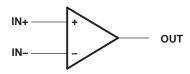


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

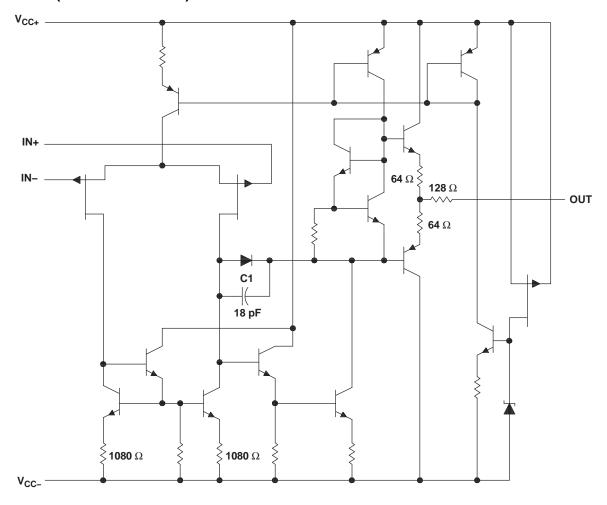




TL072 and TL074 SYMBOL (EACH AMPLIFIER)



SCHEMATIC (EACH AMPLIFIER)



All component values shown are nominal.

COMPONENT COUNT ⁽¹⁾									
COMPONENT TYPE	TL072	TL074							
Resistors	22	44							
Transistors	28	56							
JFET	4	6							
Diodes	2	4							
Capacitors	2	4							
epi-FET	2	4							

(1) Includes bias and trim circuitry

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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT		
V _{CC+}	Supply voltage ⁽²⁾				18	\/		
V _{CC} -	Supply voltage (=)			18	V			
V_{ID}	Differential input voltage ⁽³⁾			±30	V			
VI	Input voltage (2) (4)				±15	V		
	Duration of output short circuit ⁽⁵⁾				ted			
0	The arrest resistance is matical to each in at (6) (7)	TL072			97.5	°C/W		
θ_{JA}	Thermal resistance, junction-to-ambient ⁽⁶⁾ (7)	TL074			86	-0/00		
0	The arrest resistance is matical to accept (7)	TL072			38.3	900		
θ_{JC}	Thermal resistance, junction-to-case ⁽⁷⁾	TL074			51.5	°C/W		
TJ	Operating virtual junction temperature				150	°C		
T _{stg}	Storage temperature range			-65	150	°C		

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Product Folder Links: TL072-EP TL074-EP

⁽²⁾ All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}

³⁾ Differential voltages are at IN+, with respect to IN-.

⁽⁴⁾ The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.

⁽⁵⁾ The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

⁽⁶⁾ Operating at the absolute maximum T_J of 150°C can affect reliability.

⁽⁷⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



ELECTRICAL CHARACTERISTICS

 $V_{CC\pm} = \pm 15 \text{ V}$ (unless otherwise noted)

	DADAMETED	TECT CONDITIONS(1)	T (2)		TL072			TL074		LINUT	
	PARAMETER	TEST CONDITIONS ⁽¹⁾	T _A ⁽²⁾	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
V	longs offeet veltere	$V_{\Omega} = 0, R_{S} = 50 \Omega$	25°C		3	6		3	6	mV	
V_{IO}	Input offset voltage	$V_0 = 0$, $R_S = 50 \Omega$	Full range			8			8	mv	
α_{VIO}	Temperature coefficient of input offset voltage	$V_{O} = 0, R_{S} = 50 \Omega$	Full range		18			18		μV/°C	
	Input offset current	V _O = 0	25°C		5	100		5	100	pА	
I _{IO}	input onset current	v _O = 0	125°C			2			2	nA	
	Input bias current	V _O = 0	25°C		65	200		65	200	pA	
I _{IB}	input bias current	v _O = 0	125°C			20			20	nA	
V_{ICR}	Common-mode input voltage range		25°C	±11	–12 to 15		±11	-12 to 15		V	
		$R_L = 10 \text{ k}\Omega$	25°C	±12	±13.5		±12	±13.5			
V_{OM}	Maximum peak output voltage swing	R _L ≥ 10 kΩ	Full rooms	±12			±12			V	
		R _L ≥ 2 kΩ	Full range	±10			±10				
۸	Large-signal differential	$V_{\Omega} = \pm 10 \text{ V}, R_{\parallel} \ge 2 \text{ k}\Omega$	25°C	35	200		35	200		\//m\/	
A_{VD}	voltage amplification	$V_0 = \pm 10 \text{ V}, R_L \ge 2 \text{ K}\Omega$	Full range	15			15			V/mV	
B ₁	Unity-gain bandwidth		25°C		3			3		MHz	
r _i	Input resistance		25°C		10 ¹²			10 ¹²		Ω	
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR} min,$ $V_O = 0, R_S = 50 \Omega$	25°C	80	86		80	86		dB	
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC} \pm /\Delta V_{IO}$)	$V_{CC} = \pm 9 \text{ V to } \pm 15 \text{ V},$ $V_{O} = 0, R_{S} = 50 \Omega$	25°C	80	86		80	86		dB	
I _{CC}	Supply current (each amplifier)	V _O = 0, No load	25°C		1.4	2.5		1.4	2.5	mA	
V _{O1} /V _{O2}	Crosstalk attenuation	A _{VD} = 100	25°C		120	-		120		dB	

⁽¹⁾ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 3. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

OPERATING CHARACTERISTICS

 $V_{CC\pm} = \pm 15 \text{ V}, T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST	7	ΓL072		7		UNIT		
	PARAMETER	IESI	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
SR	Slew rate at unity gain	$V_I = 10 \text{ V},$ $C_L = 100 \text{ pF},$	$R_L = 2 k\Omega$, See Figure 1	8	13		8	13		V/µs
	Rise-time overshoot	$V_1 = 20 V$	$R_L = 2 k\Omega$,		0.1			0.1		μs
τ _r	factor	$C_L = 100 \text{ pF},$	See Figure 1		20			20		%
	Equivalent input noise	$R_S = 20 \Omega$	f = 1 kHz		18			18		nV/√ Hz
V _n	voltage	$R_S = 20 \Omega$	f = 10 Hz to 10 kHz		4			4		μV
In	Equivalent input noise current	$R_S = 20 \Omega$,	f = 1 kHz		0.01			0.01		pA/√Hz
THD	Total harmonic distortion	$V_{l}rms = 6 V,$ $R_{L} \ge 2 k\Omega,$ $f = 1 kHz,$	$A_{VD} = 1$, RS $\leq 1 \text{ k}\Omega$,		0.003			0.003		%

Product Folder Links: TL072-EP TL074-EP

⁽²⁾ All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is T_A = -40°C to 125°C for TL07xQ and T_A = -55°C to 125°C for TL07xM.



PARAMETER MEASUREMENT INFORMATION

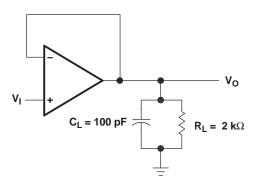


Figure 1. Unity-Gain Amplifier

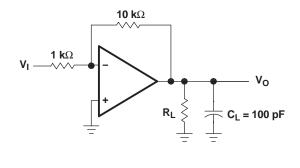


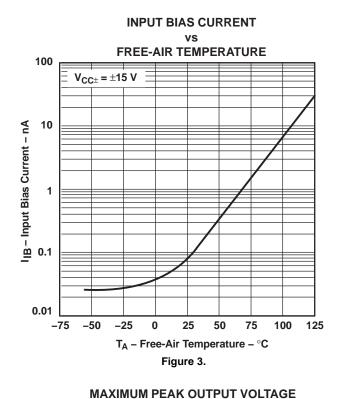
Figure 2. Gain-of-10 Inverting Amplifier

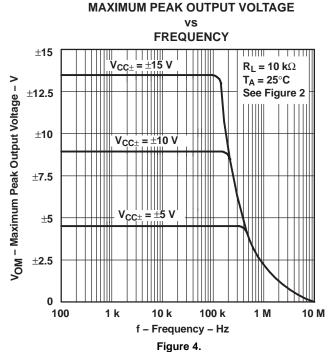
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TYPICAL CHARACTERISTICS

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.





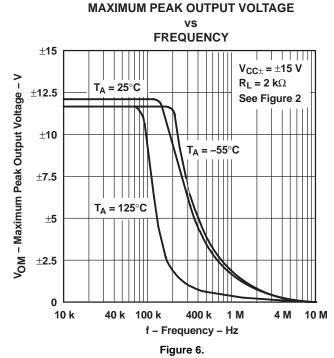
10 k

f – Frequency – Hz Figure 5.

100 k

1 M

10 M



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1 k

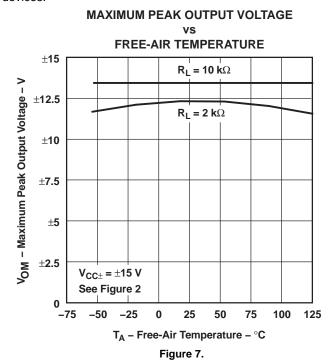
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TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



MAXIMUM PEAK OUTPUT VOLTAGE vs LOAD RESISTANCE ±15 $V_{CC\pm} = \pm 15 \text{ V}$ VOM - Maximum Peak Output Voltage - V T_A = 25°C ±12.5 See Figure 2 ±10 ±7.5 ±5 ±2.5 0.1 0.2 0.7 1 7 10 R_L – Load Resistance – $k\Omega$ Figure 8.

MAXIMUM PEAK OUTPUT VOLTAGE

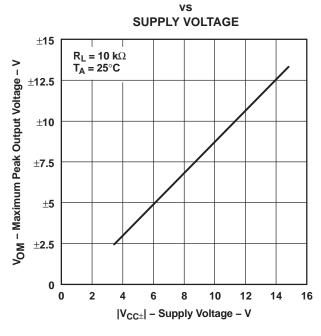
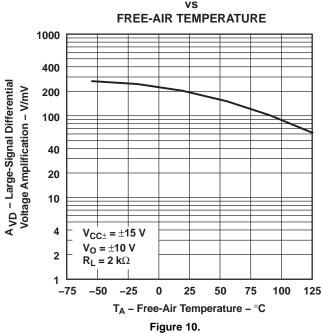


Figure 9.

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION



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0.97

100 125



TYPICAL CHARACTERISTICS (continued)

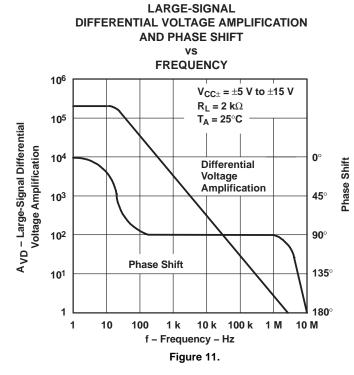
0.7 └─ -75

-50

-25

0

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



AND PHASE SHIFT vs FREE-AIR TEMPERATURE 1.03 1.3 **Unity-Gain Bandwidth** 1.02 1.2 Normalized Unity-Gain Bandwidth Normalized Phase Shift 1.01 1.1 **Phase Shift** 0.99 0.9 $V_{CC\pm} = \pm 15 \text{ V}$ 0.98 0.8 $R_L = 2 k\Omega$ f = B₁ for Phase Shift

NORMALIZED UNITY-GAIN BANDWIDTH

COMMON-MODE REJECTION RATIO

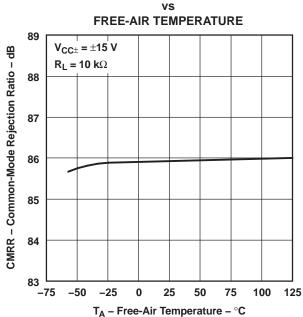


Figure 13.

SUPPLY CURRENT PER AMPLIFIER

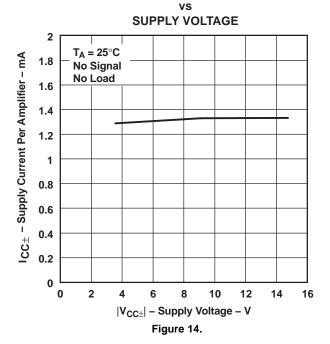
Figure 12.

50

75

25

T_A - Free-Air Temperature - °C



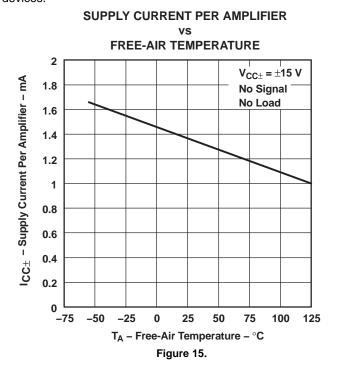
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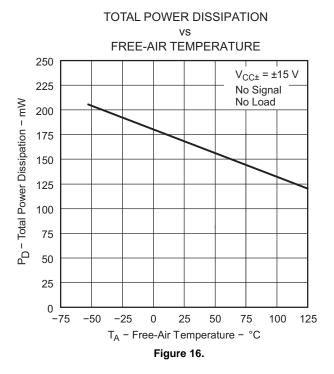
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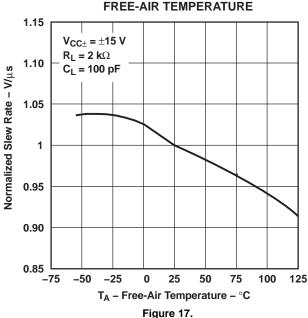
TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.





NORMALIZED SLEW RATE FREE-AIR TEMPERATURE 1.15 $V_{CC\pm} = \pm 15 \text{ V}$ $R_L = 2 k\Omega$ 1.10



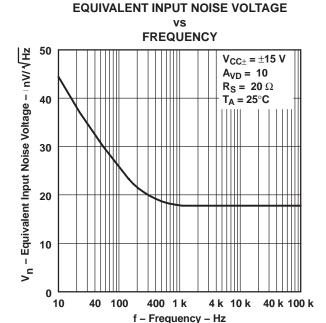


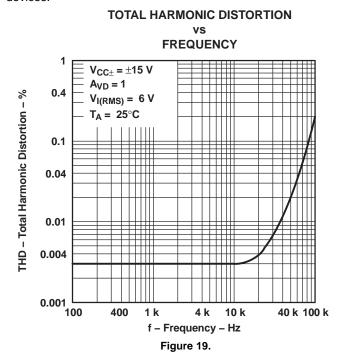
Figure 18.

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TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



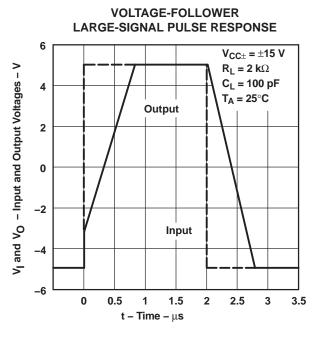
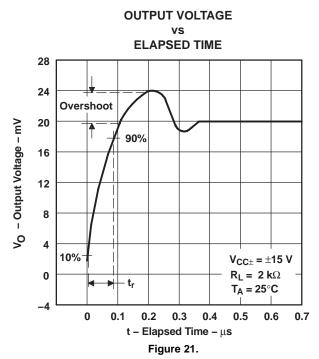


Figure 20.

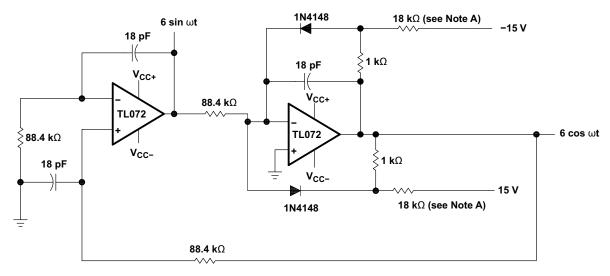


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APPLICATION INFORMATION



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 22. 100-kHz Quadrature Oscillator

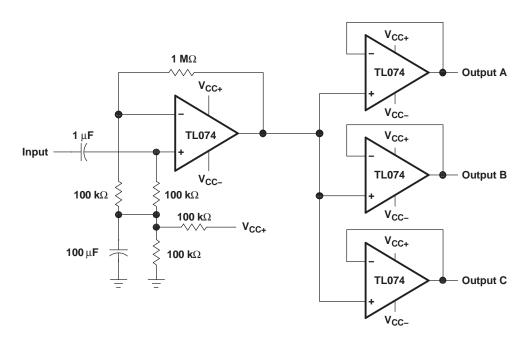


Figure 23. Audio-Distribution Amplifier

Product Folder Links: TL072-EP TL074-EP





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL072QDREP	ACTIVE	SOIC	D	8	2500	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL072Q	Samples
TL074MDEP	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
TL074MDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
TL074QDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL074Q	Samples
V62/11621-01XE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL074Q	Samples
V62/11621-02XE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
V62/11621-02XE-T	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
V62/12604-01XE	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL072Q	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TL072-EP, TL074-EP:

Military: TL072M, TL074M

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficulties are norminal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL072QDREP	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
TL074MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL074QDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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*All dimensions are nominal

1	7 til dilliononono di o momina							
	Device	Package Type Package Drawing F		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	TL072QDREP	SOIC	D	8	2500	340.5	336.1	25.0
	TL074MDREP	SOIC	D	14	2500	340.5	336.1	32.0
	TL074QDREP	SOIC	D	14	2500	340.5	336.1	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL074MDEP	D	SOIC	14	50	507	8	3940	4.32
V62/11621-02XE-T	D	SOIC	14	50	507	8	3940	4.32

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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